

# N-Channel 100 V (D-S) MOSFET

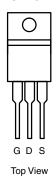
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)	
100	0.010 at V <sub>GS</sub> = 10 V	85 <sup>d</sup>	77	

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 **Definition**
- TrenchFET® Power MOSFET
- 100 % R<sub>q</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



#### TO-220AB

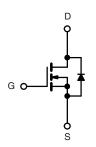


# **Ordering Information:**

SUP85N10-10P-GE3 (Lead (Pb)-free and Halogen-free)

### **APPLICATIONS**

Industrial



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V <sub>DS</sub>	100	V			
Gate-Source Voltage	V <sub>GS</sub> ± 20		v			
Continuous Drain Current (T <sub>.1</sub> = 175 °C)	T <sub>C</sub> = 25 °C	l <sub>D</sub>	85 <sup>d</sup>	Α		
Continuous Brain Current (1) = 175 O)	T <sub>C</sub> = 70 °C		83			
Pulsed Drain Current		I <sub>DM</sub>	240			
Avalanche Current	I <sub>AS</sub>	60				
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	180	mJ		
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	В	227 <sup>b</sup>	w		
	T <sub>A</sub> = 25 °C <sup>c</sup>	- P <sub>D</sub>	3.75			
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)	R <sub>thJC</sub>	0.55		

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Package limited.

Document Number: 64833 S11-2239-Rev. B, 14-Nov-11



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	100			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.5		4.5	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	μΑ
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C			250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.0080	0.0100	Ω
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.0146	0.0185	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		70		S
Dynamic <sup>b</sup>	•					
Input Capacitance	C <sub>iss</sub>			4660		pF
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 50 V, f = 1 MHz		315		
Reverse Transfer Capacitance	C <sub>rss</sub>			150		
Total Gate Charge <sup>c</sup>	$Q_g$	V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 75 A		77	120	nC
Gate-Source Charge <sup>c</sup>	$Q_{gs}$			25		
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			20		
Gate Resistance	$R_{g}$	f = 1 MHz	0.25	1.2	2.4	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 50 V, $R_L$ = 0.67 $\Omega$ $I_D$ $\cong$ 75 A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		12	20	ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			25	40	
Fall Time <sup>c</sup>	t <sub>f</sub>			8	15	
Drain-Source Body Diode Character	istics T <sub>C</sub> = 25	∘C <sub>p</sub>				
Continuous Current	I <sub>S</sub>				85	
Pulsed Current	I <sub>SM</sub>				240	Α
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 5 A, V <sub>GS</sub> = 0 V		0.8	1.5	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 5 A, dl/dt = 100 A/μs		74	115	ns
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>			6.7	10	Α
Reverse Recovery Charge	Q <sub>rr</sub>	,		250	400	nC

#### Notes:

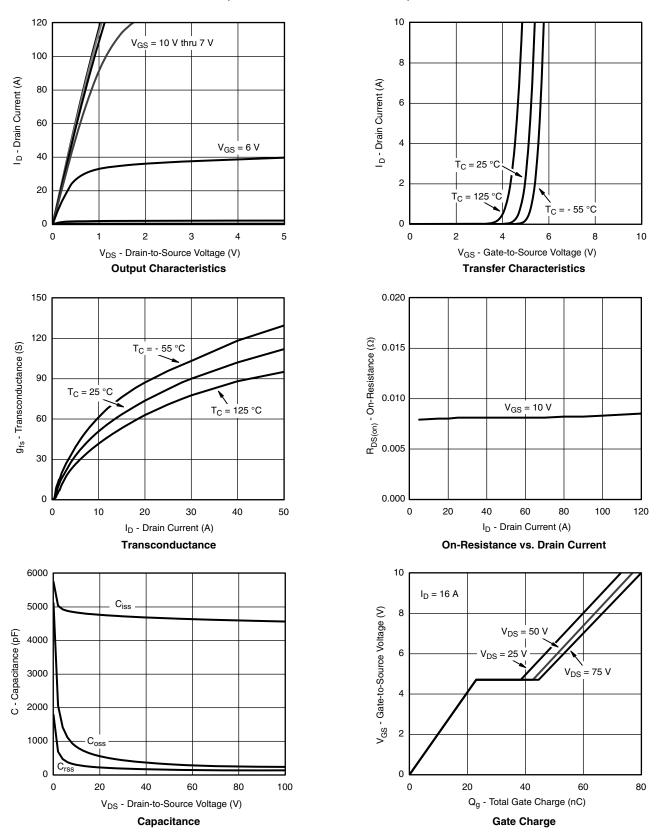
- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

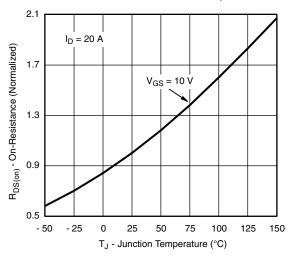




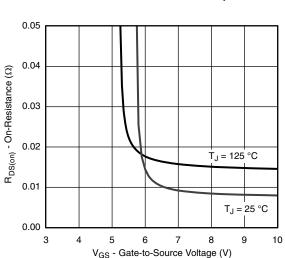
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



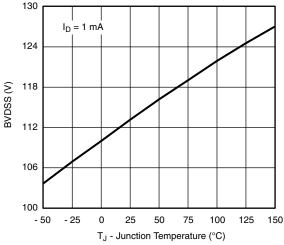
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



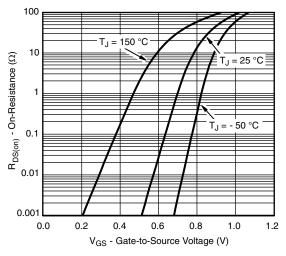
On-Resistance vs. Junction Temperature



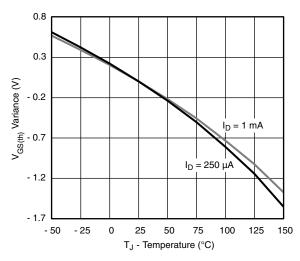
On-Resistance vs. Gate-to-Source Voltage



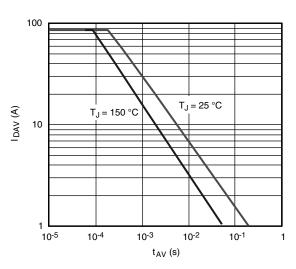
Drain Source Breakdown Voltage vs. Junction Temperature



Source-Drain Diode Forward Voltage



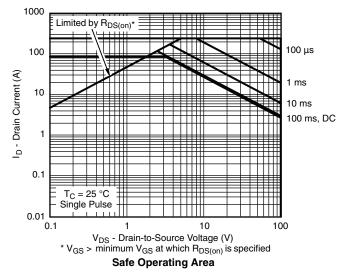
**Threshold Voltage** 

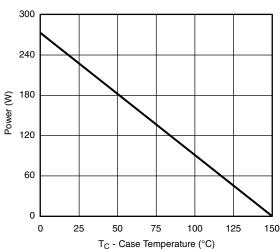


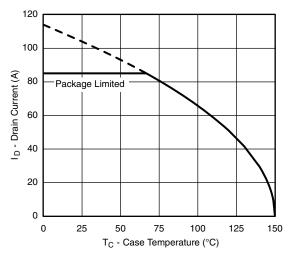
Single Pulse Avalanche Current Capability vs. Time



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





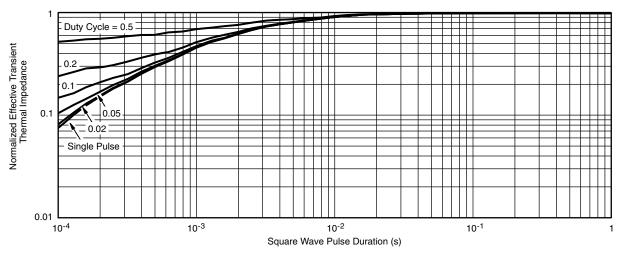


Power Derating, Junction-to-Case

**Current Derating\*** 

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max.)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heats inking is used. It is used to determine the current rating, when this rating falls below the package limit.

### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?64833.



## **Legal Disclaimer Notice**

Vishay

### **Disclaimer**

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Vishay products are not designed for use in life-saving or life-sustaining applications or any application in which the failure of the Vishay product could result in personal injury or death unless specifically qualified in writing by Vishay. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.